PROCESS FOR PRODUCING SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE

ABSTRACT OF THE DISCLOSURE

A process for producing a semiconductor device which comprises, in a process comprising mounting a semiconductor element in accordance with a flip chip bonding process, bonding the semiconductor element to a circuit board with a thermosetting resin, coating peripheral portions of the bonded semiconductor element with a photocurable resin and forming a fillet by photocuring the photocurable resin; and a semiconductor device comprising a semiconductor element mounted on a circuit board in accordance with a flip chip bonding process, wherein the semiconductor element is bonded to the circuit board with a thermosetting resin at portions directly under the semiconductor element, and a fillet is formed with a photocurable resin at peripheral portions of the semiconductor element. The semiconductor device can be efficiently produced in accordance with the flip chip bonding process and exhibits excellent resistance to heat and moisture and reliability.

Figure : 3